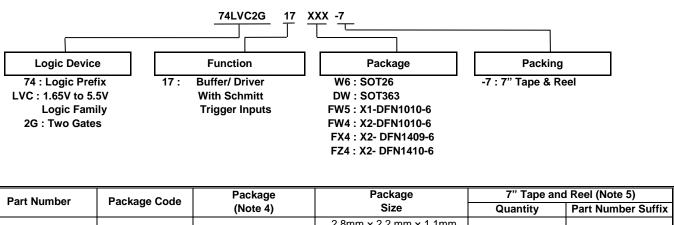


Ordering Information



			0120	Quantity	
74LVC2G17W6-7	W6	SOT26 (SC74R)	2.8mm × 2.2 mm × 1.1mm 0.95mm lead pitch	3000/Tape & Reel	-7
74LVC2G17DW-7	DW	SOT363	2.0mm × 2.0mm × 1.1mm 0.65mm lead pitch	3000/Tape & Reel	-7
74LVC2G17FW5-7	FW5	X1-DFN1010-6	10-6 1.0mm × 1.0mm × 0.5mm 0.35mm pad pitch 500		-7
74LVC2G17FW4-7	FW4	X2-DFN1010-6	1.0mm × 1.0mm × 0.4mm 0.35mm pad pitch	5000/Tape & Reel	-7
74LVC2G17FX4-7	FX4	X2-DFN1409-6 Chip Scale Alternative	1.4mm × 0.9mm × 0.4mm 0.5mm pad pitch	5000/Tape & Reel	-7
74LVC2G17FZ4-7	FZ4	X2-DFN1410-6	1.4mm × 1.0mm × 0.4mm 0.5mm pad pitch	5000/Tape & Reel	-7

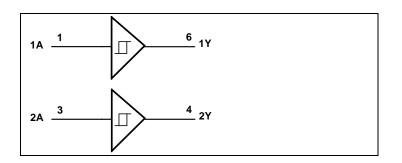
Notes: 4. Pad layout as shown on Diodes Incorporated's website at http://www.diodes.com/package-outlines.html.

5. The taping orientation is located on our website at http://www.diodes.co/datasheets/ap02007.pdf.

Pin Descriptions

Pin Name	Pin Number	Function
1A	1	Data Input
GND	2	Ground
2A	3	Data Input
2Y	4	Data Output
V _{CC}	5	Supply Voltage
1Y	6	Data Output

Logic Diagram



Function Table

Inputs	Output
Α	Y
Н	Н
L	L



Symbol	Parameter	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	kV
ESD CDM	Charged Device Model ESD Protection	1	kV
ESD MM	Machine Model ESD Protection	200	V
Vcc	Supply Voltage Range	-0.5 to +6.5	V
VI	Input Voltage Range	-0.5 to +6.5	V
Vo	Voltage Applied to Output in High Impedance or I _{OFF} State	-0.5 to +6.5	V
Vo	Voltage Applied to Output in High or Low State	-0.3 to V _{CC} +0.5	V
I _{IK}	Input Clamp Current V _I < 0	-50	mA
Ι _{ΟΚ}	Output Clamp Current V _O < 0	-50	mA
lo	Continuous Output Current	-50	mA
_	Continuous Current Through V _{DD} or GND		mA
TJ	Operating Junction Temperature	-40 to +150	°C
T _{STG}	Storage Temperature	-65 to +150	°C

Absolute Maximum Ratings (Notes 6 & 7) (@T_A = +25°C, unless otherwise specified.)

Note: 6. Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.

7. Forcing the maximum allowed voltage could cause a condition exceeding the maximum current or conversely forcing the maximum current could cause a condition exceeding the maximum voltage. The ratings of both current and voltage must be maintained within the controlled range.

Recommended Operating Conditions (Note 8) (@T_A = +25°C, unless otherwise specified.)

Symbol		Parameter	Min	Max	Unit
N/		Operating	1.65	5.5	V
Vcc	Operating Voltage	Data Retention Only	1.5	—	V
VI	Input Voltage		0	5.5	V
Vo	Output Voltage		0	Vcc	V
		V _{CC} = 1.65V	—	-4	
	I _{OH} High-Level Output Current	V _{CC} = 2.3V	_	-8	
Іон		V 2V	—	-16	mA
		$V_{CC} = 3V$	—	-24	
		$V_{CC} = 4.5V$	—	-32	
		V _{CC} = 1.65V	—	4	
		$V_{CC} = 2.3 V$	—	8	
IOL	Low-Level Output Current		—	16	mA
		$V_{CC} = 3V$	—	24	
		$V_{CC} = 4.5V$	—	32	
		$V_{CC} = 1.8V \pm 0.15V, 2.5V \pm 0.2V$	—	20	
Δt/ΔV	Input Transition Rise or Fall Rate	nput Transition Rise or Fall Rate $V_{CC} = 3.3V \pm 0.3V$		10	ns/V
		$V_{CC} = 5V \pm 0.5V$	—	5	1
TA	Operating Free-air Temperature		-40	+125	°C

Note: 8. Unused inputs should be held at V_{CC} or Ground.



Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Cumula al	Deveryoter	Test Canditions	N N	-40°C to	o +85°C	-40°C to	+125°C	11
Symbol	Parameter	Test Conditions	Vcc	Min	Max	Min	Max	Unit
			1.8V	0.70	1.50	0.70	1.70	
			2.3V	1.00	1.80	1.00	2.00	
V _{T+}	Positive-going Input Threshold Voltage	—	3V	1.30	2.20	1.30	2.40	V
	Theshold Voltage		4.5V	1.90	3.10	1.90	3.30	
			5.5V	2.20	3.60	2.20	3.80	
			1.8V	0.25	0.90	0.25	1.10	
			2.3V	0.40	1.15	0.4	1.35	
V _T .	Negative-going Input Threshold Voltage	—	3V	0.60	1.50	0.6	1.7	V
	Theshold Voltage		4.5V	1.00	2.00	1	2.2	
			5.5V	1.20	2.30	1.2	2.5	
			1.8V	0.15	1.00	0.15	1.2	
			2.3V	0.25	1.10	0.25	1.3	
ΔV_{T}	T Hysteresis (V _{T+} - V _{T-)}	—	3V	0.40	1.20	0.40	1.40	V
			4.5V	0.60	1.50	0.60	1.70	
			5.5V	0.70	1.70	0.70	1.90	
		I _{OH} = -100μA	1.65V to 5.5V	V _{CC} – 0.1	-	V _{CC} - 0.1	_	
		I _{OH} = -4mA	1.65V	1.2		0.95		
		I _{OH} = -8mA	2.3V	1.9	-	1.7	_	v
V _{OH}	High-Level Output Voltage	I _{OH} = -16mA	0) (2.4	-	1.9	-	v
		I _{OH} = -24mA	3V	2.3	-	2.0	_	
		I _{OH} = -32mA	4.5V	3.8	-	3.4	_	
		I _{OL} = 100μA	1.65V to 5.5V	—	0.1	—	0.10	
		$I_{OL} = 4mA$	1.65V	—	0.45	—	0.70	
		I _{OL} = 8mA	2.3V	—	0.3	—	0.45	v
V _{OL}	Low-Level Output Voltage	I _{OL} = 16mA	0) (—	0.4	_	0.60	v
		$I_{OL} = 24 \text{mA}$	3V	—	0.55	_	0.80	
		I _{OL} = 32mA	4.5V	—	0.55	—	0.80	
II.	Input Current	$V_1 = 5.5V$ or GND	0 to 5.5V	—	± 5	—	± 20	μA
I _{OFF}	Power Down Leakage Current	$V_{\rm I}$ or $V_{\rm O}$ = 5.5V	0	_	± 10	_	± 20	μA
Icc	Supply Current	$V_{I} = 5.5V$ or GND, $I_{O} = 0$	1.65V to 5.5V	_	10	_	40	μA



Symbol	Parameter	Package	Conditions	Min	Тур	Max	Unit
CI	Input Capacitance	Typical of all packages	$V_{CC} = 3.3V$ $V_{I} = V_{CC}$ or GND	_	3.5	_	pF
		SOT26		—	204	—	
		SOT363		—	371	—	
	Thermal Resistance Junction-to-	X2-DFN1410-6		—	430	—	
θ_{JA}	Ambient	X2-DFN1409-6	(Note 9)	_	450	_	°C/W
		X1-DFN1010-6		_	495	_	
		X2-DFN1010-6		_	510	_	
		SOT26		_	52	_	
		SOT363		_	143	—	
-	Thermal Resistance Junction-to-	X2-DFN1410-6		—	190	—	
θ_{JC}	Case	X2-DFN1409-6	(Note 9)	_	225	_	°C/W
		X1-DFN1010-6		_	245	_	
		X2-DFN1010-6	7		250		

Package Characteristics (@T_A = +25°C, V_{CC} = 3.3V, unless otherwise specified.)

Note: 9. Test condition for all packages: Device mounted on FR-4 substrate PC board, 2oz copper with minimum recommended pad layout.

Switching Characteristics

$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$	$C, C_{L} = 30 pF$	or 50pF (See Figu	ure 1)								
Parameter	From	From TO (Input) (OUTPUT)		⊧ 1.8V .15V	••	= 2.5V).2V	••	= 3.3V).3V	V _{CC} ±0	= 5V 0.5V	Unit
	(input)	(001901)	Min	Max	Min	Max	Min	Мах	Min	Max	
t _{PD}	А	Y	0.5	10.5	0.5	6.5	0.5	5.7	0.5	4.3	ns

$T_A = -40^{\circ}C$ to +125°C, $C_L = 30pF$ or 50pF (See Figure 1)

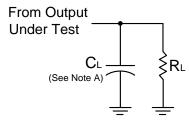
Parameter	From (Input)	TO (OUTPUT)		= 1.8V .15V		: 2.5V).2V		= 3.3V).3V		= 5V).5V	Unit
	(input)	(001-01)	Min	Мах	Min	Max	Min	Мах	Min	Max	
t _{PD}	А	Y	0.5	13.1	0.5	8.5	0.5	7.1	0.5	5.4	ns

Operating Characteristics

T _A = +25°C							
	Parameter		V _{CC} = 1.8V	V _{CC} = 2.5V	V _{CC} = 3.3V	V _{CC} = 5V	11
	Farameter	Conditions	Тур	Тур	Тур	Тур	Unit
C _{PD}	Power Dissipation Capacitance	f = 10MHz	17	19	20	21	pF



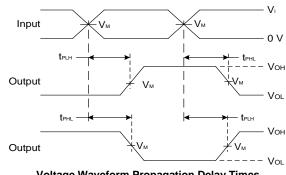
Parameter Measurement Information



N N	Inp	outs	V	<u>^</u>	P	
V _{cc}	VI	t _R /t _F	V _M	CL	RL	
1.8V±0.15V	Vcc	≤2ns	V _{CC} /2	30pF	1kΩ	
2.5V±0.2V	V _{CC}	≤2ns	V _{CC} /2	30pF	500Ω	
3.3V±0.3V	3V	≤2.5ns	1.5V	50pF	500Ω	
5V±0.5V	Vcc	≤2.5ns	V _{CC} /2	50pF	500Ω	



Voltage Waveform Pulse Duration



Voltage Waveform Propagation Delay Times Inverting and Non Inverting Outputs

Figure 1 Load Circuit and Voltage Waveforms

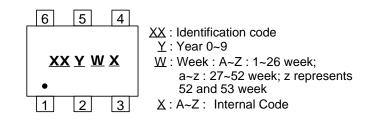
- A. Includes test lead and test apparatus capacitance. B. All pulses are supplied at pulse repetition rate $\leq\,$ 10MHz. C. Inputs are measured separately one transition per measurement.
- D. tPLH and tPHL are the same as tPD.

Notes:



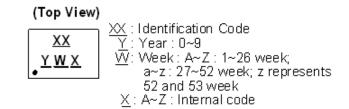
Marking Information

(1) SOT26 (SC74R), SOT363



Part Number	Package	Identification Code
74LVC2G17W6-7	SOT26 (SC74R)	Z6
74LVC2G17DW-7	SOT363	Z6

(2) X1-DFN1010-6, X2-DFN1010-6, X2-DFN1409-6, X2-DFN1410-6

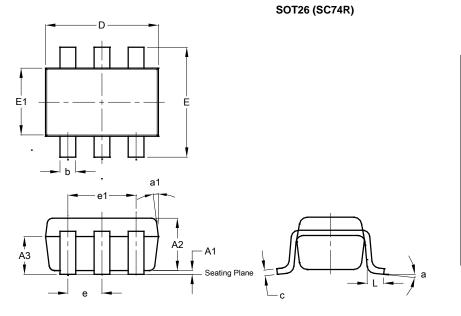


Part Number	Package	Identification Code
74LVC2G17FW4-7	X2-DFN1010-6	Z6
74LVC2G17FW5-7	X1-DFN1010-6	W6
74LVC2G17FX4-7	X2-DFN1409-6	X6
74LVC2G17FZ4-7	X2-DFN1410-6	Z6

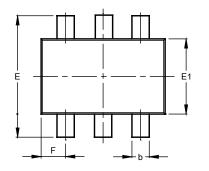


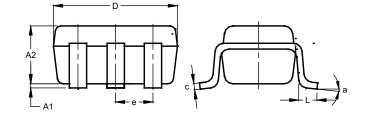
Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.



	SOT26	1807	
Dim	Min	Max	Тур
A1	0.013	0.10	0.05
A2	1.00	1.30	1.10
A3	0.70	0.80	0.75
b	0.35	0.50	0.38
С	0.10	0.20	0.15
D	2.90	3.10	3.00
е	_		0.95
e1	_		1.90
Е	2.70	3.00	2.80
E1	1.50	1.70	1.60
L	0.35	0.55	0.40
а	_		8°
a1		_	7°
All Dimensions in mm			





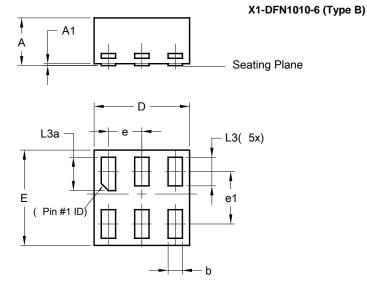
SOT363				
Dim	Min	Max	Тур	
A1	0.00	0.10	0.05	
A2	0.90	1.00	0.95	
b	0.10	0.30	0.25	
С	0.10	0.22	0.11	
D	1.80	2.20	2.15	
E	2.00	2.20	2.10	
E1	1.15	1.35	1.30	
е	C).650 B	SC	
F	0.40	0.45	0.425	
L	0.25	0.40	0.30	
а	0°	8°		
All Dimensions in mm				

SOT363

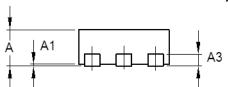


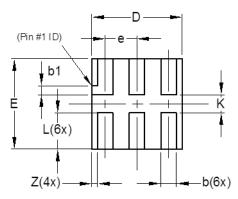
Package Outline Dimensions (continued)

Please see http://www.diodes.com/package-outlines.html for the latest version.



	X1-DFN1010-6 (Type B)			
Dim	Min	Max	Тур	
Α	_	0.50	0.39	
A1	_	0.04	—	
b	0.12	0.20	0.15	
D	0.95	1.050	1.00	
Е	0.95	1.050	1.00	
е	0.35 BSC			
e1	0.55 BSC			
L3	0.27	0.30	0.30	
L3a	0.32	0.40	0.35	
All	All Dimensions in mm			





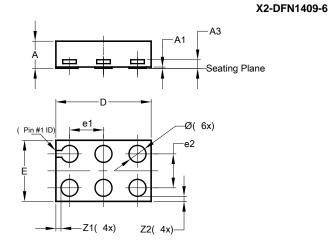
X2-DFN1010-6

X2-DFN1010-6					
Dim	Dim Min Max Typ				
Α	—	0.40	0.39		
A1	0.00	0.05	0.02		
A3	—	—	0.13		
b	0.14	0.20	0.17		
b1	0.05	0.15	0.10		
D	0.95	1.05	1.00		
Е	0.95	1.05	1.00		
е	—	—	0.35		
L	0.35	0.45	0.40		
К	0.15	_	—		
Z			0.065		
All Dimensions in mm					

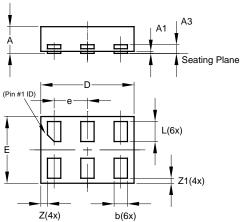


Package Outline Dimensions (continued)

Please see http://www.diodes.com/package-outlines.html for the latest version.



X2-DFN1409-6 Dim Min Max Тур 0.40 0.39 Α A1 0 0.05 0.02 A3 0.13 _ _ Ø 0.20 0.30 0.25 D 1.35 1.45 1.40 Ε 0.85 0.95 0.90 e1 0.50 e2 0.50 **Z**1 0.075 ____ Z2 0.075 All Dimensions in mm



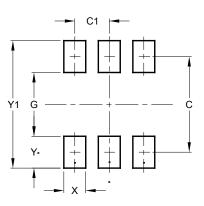
X2-DFN1410-6

X2-DFN1410-6					
Dim	m Min Max Typ				
Α	—	0.40	0.39		
A1	0.00	0.05	0.02		
A3	_		0.13		
b	0.15	0.25	0.20		
D	1.35	1.45	1.40		
Е	0.95	1.05	1.00		
е	_		0.50		
L	0.25	0.35	0.30		
Z	—		0.10		
Z1	0.045	0.105	0.075		
All Dimensions in mm					



Suggested Pad Layout

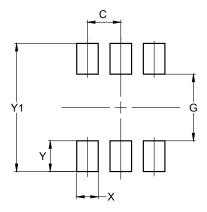
Please see http://www.diodes.com/package-outlines.html for the latest version.



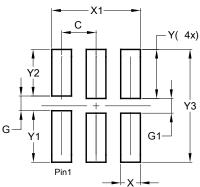
SOT26 (SC74R)	
---------------	--

Dimensions	Value (in mm)
С	2.40
C1	0.95
G	1.60
Х	0.55
Y	0.80
Y1	3.20

SOT363



Dimensions	Value (in mm)
С	0.650
G	1.300
Х	0.420
Y	0.600
Y1	2.500



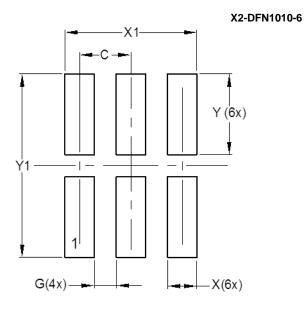
X1-DFN1010-6 (Type B)

Dimensions	Value	
•	(in mm)	
С	0.350	
G	0.150	
G1	0.150	
Х	0.200	
X1	0.900	
Y	0.500	
Y1	0.525	
Y2	0.475	
Y3	1.150	

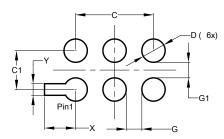


Suggested Pad Layout (continued)

Please see http://www.diodes.com/package-outlines.html for the latest version.

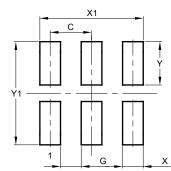


Dimensions	Value (in mm)
С	0.350
G	0.150
х	0.200
X1	0.900
Y	0.550
Y1	1.250



X2-C)FN ²	1409	-6
72-L		1703	-0

Dimensions	Value (in mm)
С	1.000
C1	0.500
D	0.300
G	0.200
G1	0.200
Х	0.400
Ŷ	0.150



X2-DFN1410-6

Dimensions	Value (in mm)
С	0.500
G	0.250
Х	0.250
X1	1.250
Y	0.525
Y1	1.250



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